Serial Number: 10/772,606 Filing Date: February 5, 2004

7

Title: INTEGRATED CIRCUITS USING OPTICAL FIBER INTERCONNECTS FORMED THROUGH A SEMICONDUCTOR WAFER

In the Specification

Please amend the first paragraph beginning on page 1, line 5, with the following rewritten paragragh:

This application is a Divisional of U.S. Application No. 09/650,569, filed August 30, 2000, now U.S. Patent No. 6,723,577, which is a Continuation of U.S. application, Serial No. 09/031,975, filed on February 26, 1998, now U.S. Patent No. 6,150,188, both of which are incorporated herein by reference.

Page 2 Dkt: 303.390US4